Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2847

DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance : $RDS(ON) = 1.1 \Omega(typ.)$

• High forward transfer admittance : $|Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720 V)$

• Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit | |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 900 | V | |
| Drain-gate voltage (R _{GS} = 20 kΩ) | | V_{DGR} | 900 | V | |
| Gate-source voltage | | V_{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | I _D | 8 | Α | |
| | Pulse (Note 1) | I _{DP} | 24 | Α | |
| Drain power dissipatio | n (Tc = 25°C) | P_{D} | 85 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 799 | mJ | |
| Avalanche current | | I _{AR} | 8 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 8.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |

15.8±0.5 3.6±0.2 3.5 1.0+0.25 1.0+0.25 2.0 1. GATE 2. DRAIN 3. SOURCE JEDEC JEITA TOSHIBA 2-16F1B

Weight: 5.8 g (typ.)

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 1.47 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 41.6 | °C/W |

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 22.9 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

2SK2847



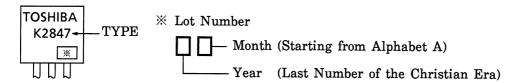
Electrical Characteristics (Ta = 25°C)

| Charac | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|-----------------|----------------------|--|-----|------|-----|------|
| Gate leakage cu | ırrent | I _{GSS} | V _{GS} = ±30 V, V _{DS} = 0 V | _ | _ | ±10 | μΑ |
| Gate-source bro | eakdown voltage | V (BR) GSS | I _G = ±10 μA, V _{DS} = 0 V | ±30 | _ | _ | V |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = 720 V, V _{GS} = 0 V | _ | _ | 100 | μΑ |
| Drain-source br | eakdown voltage | V (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 900 | _ | _ | V |
| Gate threshold v | /oltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 2.0 | _ | 4.0 | V |
| Drain-source O | N resistance | R _{DS (ON)} | V _{GS} = 10 V, I _D = 4 A | _ | 1.1 | 1.4 | Ω |
| Forward transfe | r admittance | Y _{fs} | V _{DS} = 15 V, I _D = 4 A | 3.0 | 7.0 | _ | S |
| Input capacitano | e | C _{iss} | | _ | 2040 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz | _ | 45 | _ | pF |
| Output capacitance | | C _{oss} | | _ | 190 | _ | |
| Switching time | Rise time | t _r | $V_{GS} \stackrel{10V}{\underset{0V}{\longrightarrow}} \stackrel{I_{D}=4A}{\underset{R_{L}}{\longrightarrow}} V_{OUT}$ $4.7\Omega {\underset{=}{\longrightarrow}} V_{DD}$ $= 400V$ $Duty \leq 1\%, \ t_{W} = 10 \mu s$ | _ | 25 | _ | - ns |
| | Turn-on time | t _{on} | | _ | 60 | _ | |
| | Fall time | t _f | | _ | 20 | _ | |
| | Turn-off time | t _{off} | | _ | 95 | _ | |
| Total gate charge (gate-source plus gate-drain) | | Qg | | | 58 | | |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$ | | 32 | _ | nC |
| Gate-drain ("miller") Charge | | Q_{gd} | | | 26 | _ | |

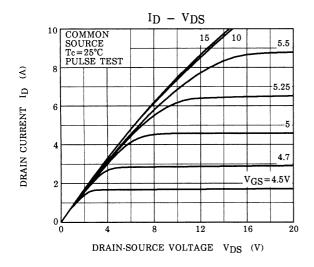
Source-Drain Ratings and Characteristics (Ta = 25°C)

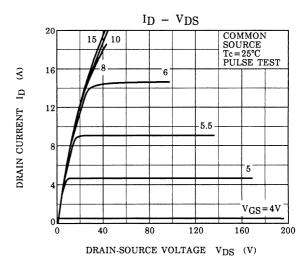
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 8 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 24 | Α |
| Forward voltage (diode) | V _{DSF} | I _{DR} = 8 A, V _{GS} = 0 V | _ | _ | -1.9 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 8 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs | _ | 1650 | - | ns |
| Reverse recovery charge | Q _{rr} | dl _{DR} / dt = 100 A / μs | _ | 21 | _ | μC |

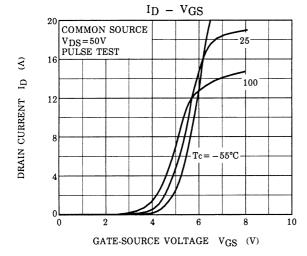
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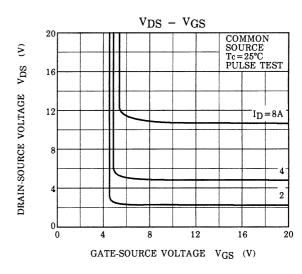


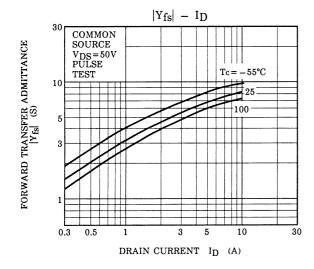
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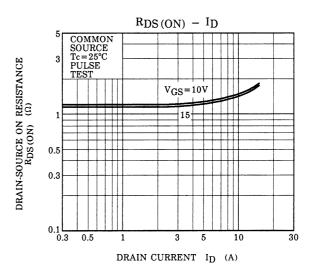




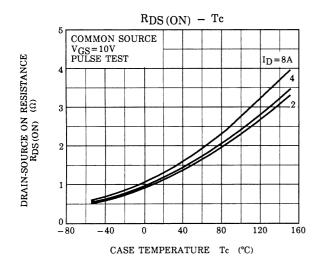


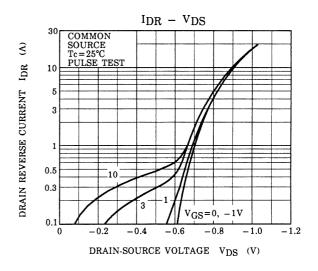


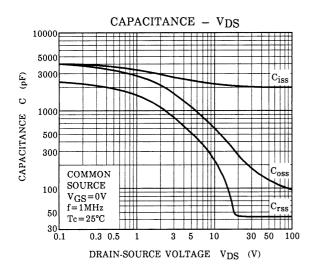


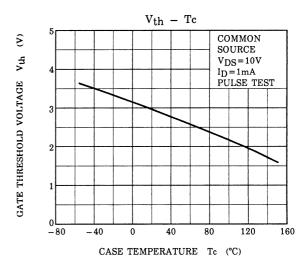


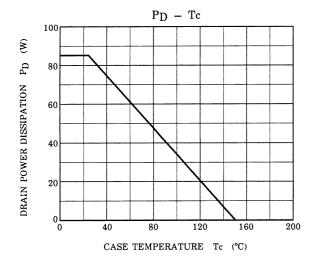
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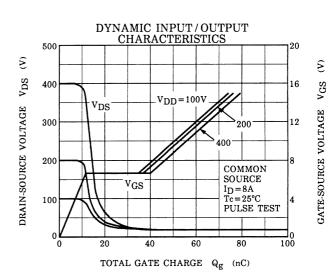




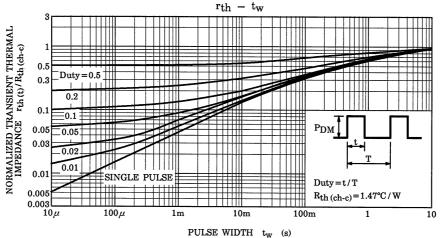


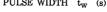


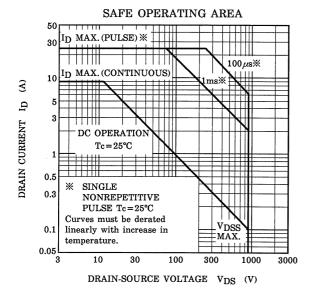


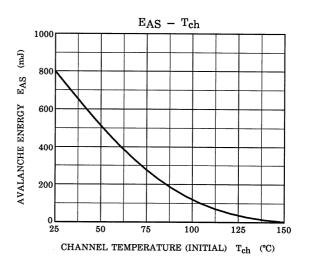


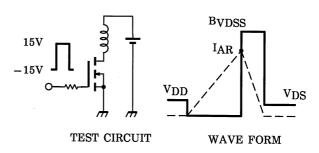
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$$\begin{split} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 22.9~mH \end{split} \tag{EAS}$$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

RESTRICTIONS ON PRODUCT USE

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